Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP 245 G2 Notebook PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery Pack,RTC</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Automatic Screw Driver</td>
<td>Philip #1</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassembly and remove Service Door
2. Remove battery module
3. Disassemble Motherboard and thermal module
4. Disassemble Keyboard and touchpad
5. Disassemble C cover
6. Disassemble LCD module
7. 
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module
3.23 Remove service door
3.24 LCD module set disassembly
3.25 Top case disassembly
3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly
Work Instructs

Document No. : Disassembly WI                             Step : 1
Name              : Get Battery                             Date : 2013-11-13

Step:

1. Remove Battery pack.
2. Loosen screws in D cover,

Fixtures list:

<table>
<thead>
<tr>
<th>Fixture list(Fixture standard)</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1</td>
<td>1</td>
</tr>
</tbody>
</table>

Point for attention: If finding some defects, notice the gaffer and assess.
## Work Instructs

**Document No:** Disassembly WI  
**Name:** Disassemble C cover  
**Date:** 2013-11-13  
**Step:** 2

<table>
<thead>
<tr>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Point for attention:** If finding some defects, notice the gaffer and assess.

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**Step:**

1. Remove service door, get memory card, WLAN card.
2. Open the notebook.
   Disassemble the C cover.
Work Instructs

Document No.: Disassembly WI  Step: 3
Name: Disassemble C cover  Date: 2013-11-13

Fixtures list (Fixture standard)  Qty  Fixtures list (Fixture standard)  Qty
Philip #1  1

Point for attention: If finding some defects, notice the gaffer and assess.
**Work Instructs**

<table>
<thead>
<tr>
<th>Document No. : Disassembly WI</th>
<th>Step : 4</th>
</tr>
</thead>
<tbody>
<tr>
<td>Name : Disassemble MB</td>
<td>Date : 2013-11-13</td>
</tr>
</tbody>
</table>

**Step:**

1. Loosen screws on MB.
2. Get mother board.

<table>
<thead>
<tr>
<th>Fixture list(Fixture standard)</th>
<th>Qty</th>
<th>Fixture list(Fixture standard)</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1</td>
<td>1</td>
<td></td>
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</tr>
</tbody>
</table>

*Point for attention: If finding some defects, notice the gaffer and assess.*
**Work Instructs**

**Document No.**: Disassembly WI  
**Name**: Disassemble MB  
**Step**: 5  
**Date**: 2013-11-13

**Fixture list (Fixture standard)**  
**Qty**  
**Cross Head of Screws Driver**  
1

**Point for attention**: If finding some defects, notice the gaffer and assess.

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**Step:**

1. Get the HDD, ODD and USB board from C cover.
2. Disassemble thermal module.
Step:

1. Get the thermal module and mother board.

Point for attention: If finding some defects, notice the gaffer and assess.
Work Instructs

Document No. : Disassembly WI  
Name : Disassemble D cover  
Step : 7  
Date : 2013-11-13

Point for attention: If finding some defects, notice the gaffer and assess.

Step:

1. Tear down DC in cable, speaker.
2. Disassemble LCD panel and Touchscreen.
Work Instructs

Document No.: Disassembly WI
Name: Disassemble LCD Module
Step: 8
Date: 2013-11-13

Step:
Disassemble LCD module,

<table>
<thead>
<tr>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Point for attention: If finding some defects, notice the gaffer and assess.
Work Instructs

Document No.: Disassembly WI  Step: 9
Name: Disassemble LCD Module  Date: 2013-11-13

<table>
<thead>
<tr>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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Step:

Tear down hinges, get the LCD panel.
Work Instructs

Document No. : Disassembly WI
Name : Disassemble LCD Module
Step : 10
Date : 2013-11-13

Step:
Disassemble Camera. LVDS Cable.

<table>
<thead>
<tr>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
<th>Fixture list (Fixture standard)</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1</td>
<td>1</td>
<td></td>
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